

ABSTRACT

An efficient adhesive system and method for a ball grid array semiconductor device package which allows for better encapsulation are disclosed. A material is added between a die and a circuit board tape, which is oriented perpendicular to a conventional two-piece tape system used to attached the die to the circuit board. The material is located across from a gate which injects encapsulation material to form a package and acts as a diversion dam causing a compound injected during encapsulation to fill a wirebond slot last and avoid a compound overflow which might otherwise damage the ball grid array.